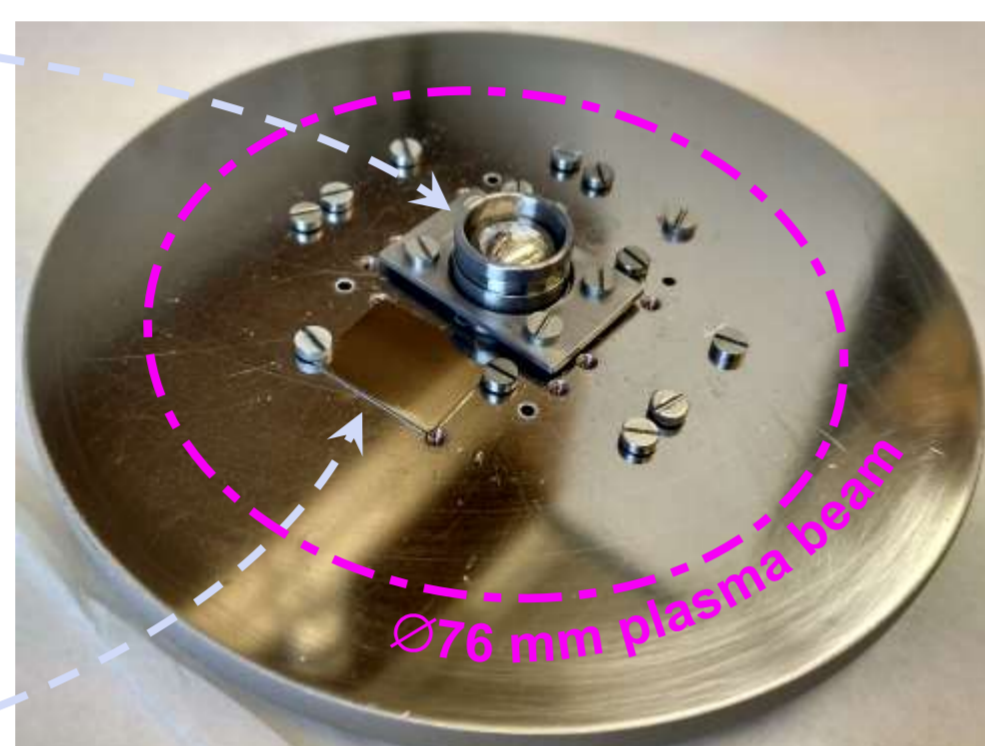


## Motivation

- **Liquid metals as alternative to solid W divertor?** (see, e.g. [1])
  - Avoid brittle failure, melt damage, neutron damage...
- **Tin: low evaporation rate up to about 1000 K, no known solid hydrides, endothermic H solubility [2]**
  - Promising heat load handling capability [1, 3]
  - Very little actual data on D retention
  - Indication for chemical erosion by volatile SnD<sub>4</sub> formation [4, 5]
- **Systematic study below and above melting point of Sn (505 K):**
  - D retention and release after Sn exposure to D plasma
  - Sn net erosion and nearby re-deposition by mass loss measurements and Mo witness samples

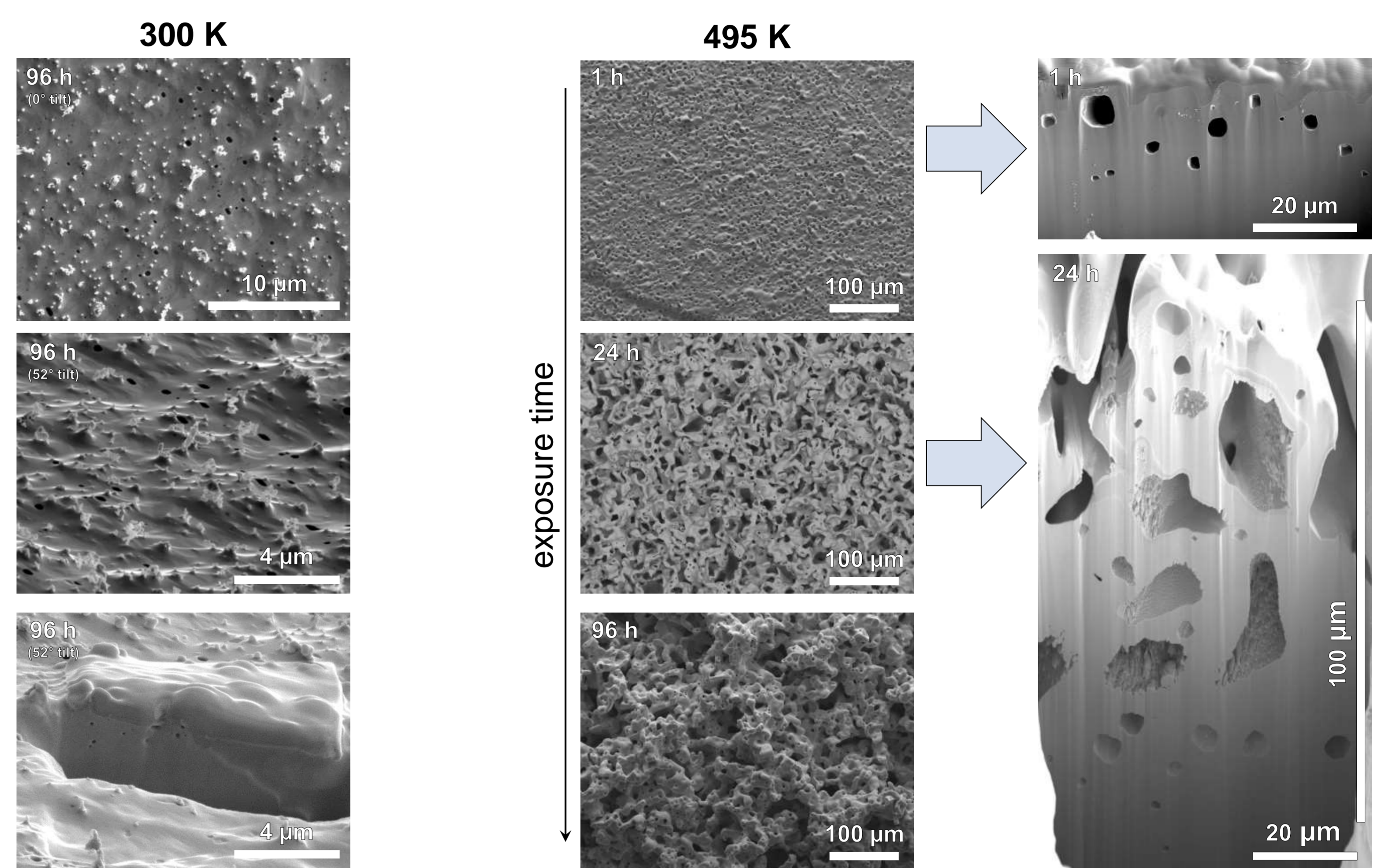
## Experiment details

- **Low-temperature ECR plasma source PlaQ [6]**
  - Ion flux:  $\sim 1.2 \times 10^{20}$  D/m<sup>2</sup>s (97% from D<sub>3</sub><sup>+</sup>)
  - -25 V bias (+ 7 V plasma potential):  $\sim 11$  eV/D from D<sub>3</sub><sup>+</sup>
  - $\sim 100$ x more D<sup>0</sup> than D ions
  - Absolute temperature accuracy:  $\pm 5$  K
- **Sn samples:**
  - 99.999% purity (Kurt J. Lesker Co.)
  - Cu crucible with  $\sim 2$   $\mu$ m W coating, 10 mm inner diameter
  - Pre-molten & degassed in vacuum at 523 K for 2 h, slow heating and cooling
  - Typical mass of Sn:  $\sim 2.6$  g
- **Mo witness samples:**
  - $\sim 12 \times 15 \times 0.5$  mm<sup>3</sup>, mechanically polished



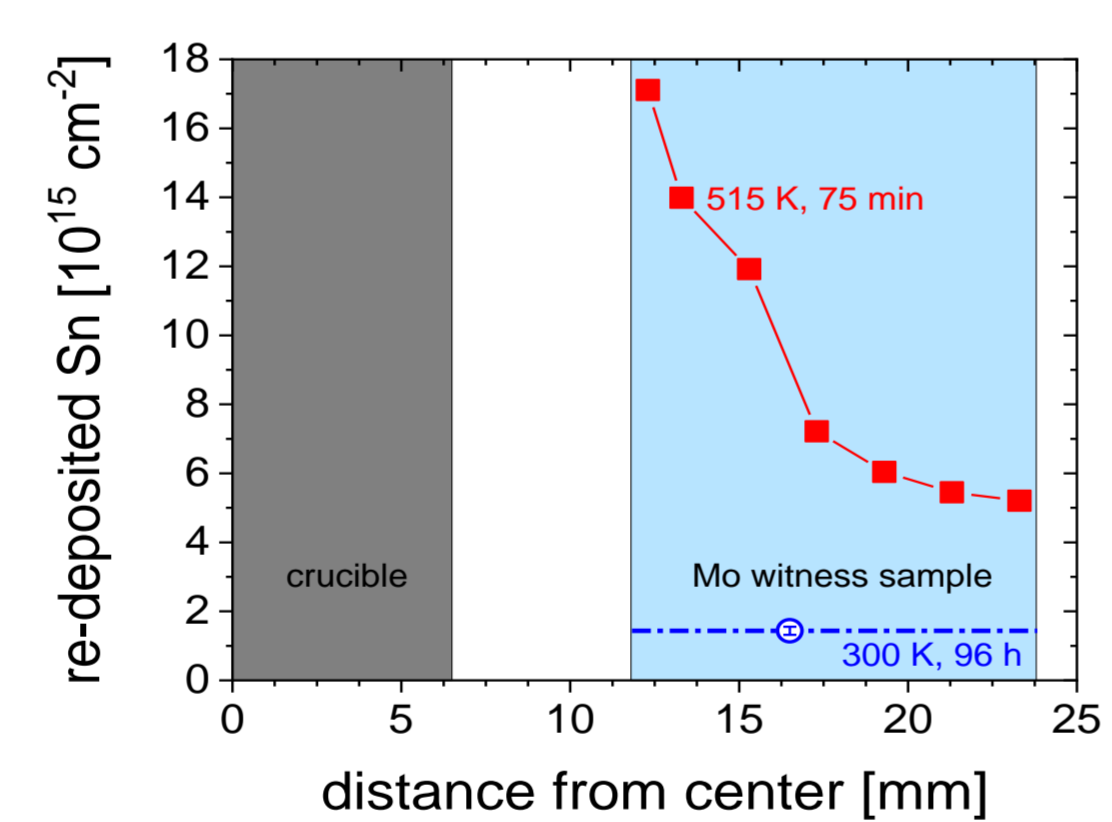
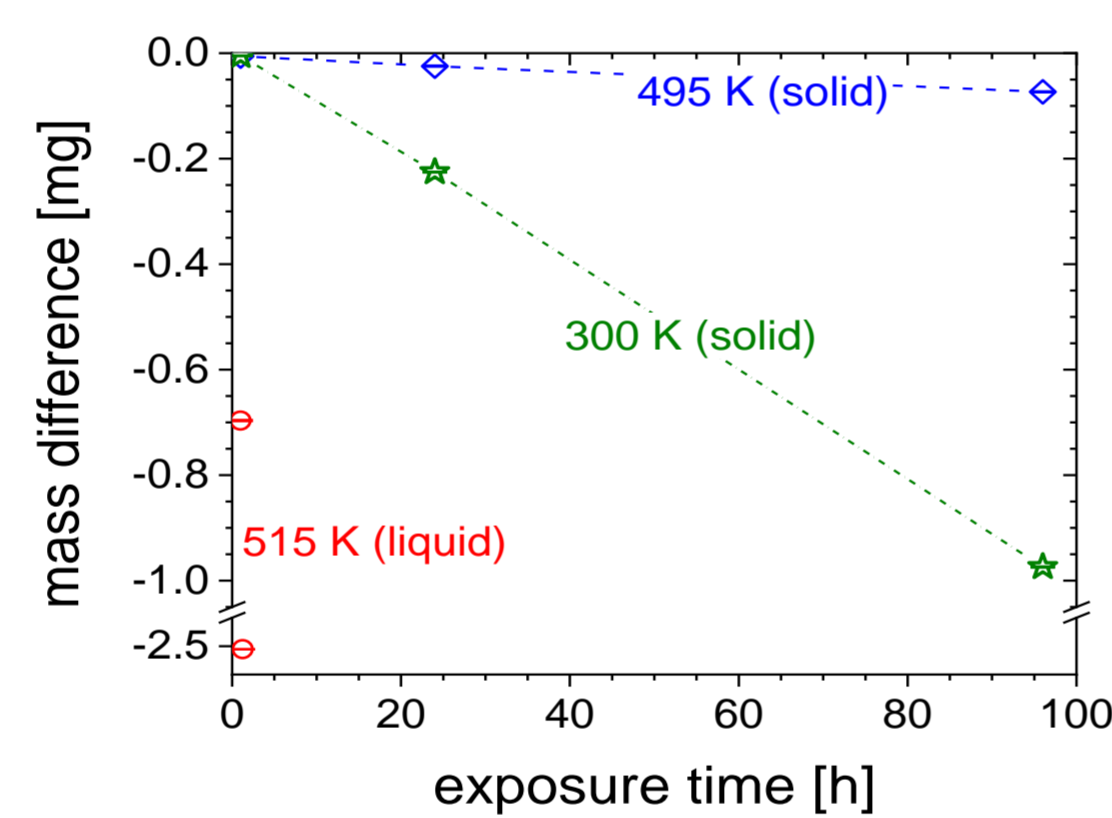
## Evolution of Sn surface

- **300 K:**
  - Small bubbles near surface; unstable during electron beam imaging!
  - Dune-like surface, ridges crowned by Cu- and Fe-rich precipitates  $\rightarrow$  erosion morphology
- **495 K:**
  - Formation of sponge-like, highly porous layer  $\rightarrow$  up to 250-500  $\mu$ m thick after 96 hours
- **515 K:**
  - Sn droplet quickly starts wetting W coating, then rises out of crucible  $\rightarrow$  large cavity below Sn
  - Gas amount in cavity  $\sim 2000$ x larger than anticipated based on diffusion  $\rightarrow$  convection in melt
  - Smaller bubbles found in Sn  $\rightarrow$  rise to surface and burst, or get dragged to bottom by melt motion



## Mass loss & re-deposition

- **SDTrimSP 6.00 [7] simulations:**
  - Sputtering threshold  $\geq 50$  eV
  - Maximum ion energy (D<sup>+</sup>):  $\sim 32$  eV
  - $\rightarrow$  expected: chemical erosion (if any)
- **300 K:**
  - Strong mass loss by chemical erosion
  - Small re-deposition on Mo witness sample
- **495 K:**
  - Much smaller erosion
  - $\rightarrow$  sponge-like structure!
  - No measurable re-deposition
  - Erosion of small Sn droplets from 2<sup>nd</sup> Mo sample
- **515 K:**
  - Very large mass loss, strong scatter
  - $\rightarrow$  ejection of Sn droplets due to bursting gas bubbles
  - Sn droplets found on witness samples



## Conclusions

- **Large part of D retention in Sn apparently within gas bubbles**
  - Small, near-surface bubbles for 300 K exposure
  - Thick, sponge-like, porous layer for 495 K exposure
  - Large gas bubble below Sn droplet for 515 K exposure
- **Release practically all D up to melting point (505 K) for solid Sn exposure**
- **D release until long after melting for liquid Sn exposure**
- **Strong chemical erosion at 300 K, weaker at 495 K**
  - Possibly linked to formation of sponge-like layer
  - Some re-deposition of Sn on Mo at 300 K
  - 495 K: no measurable Sn re-deposition; erosion of small Sn droplets
- **Erosion at 515 K dominated by droplet ejection due to bubble bursts**
  - Deposition of Sn spray on Mo sample
- **Wetting of W by Sn at 515 K under D plasma exposure  $\rightarrow$  oxide removal?**

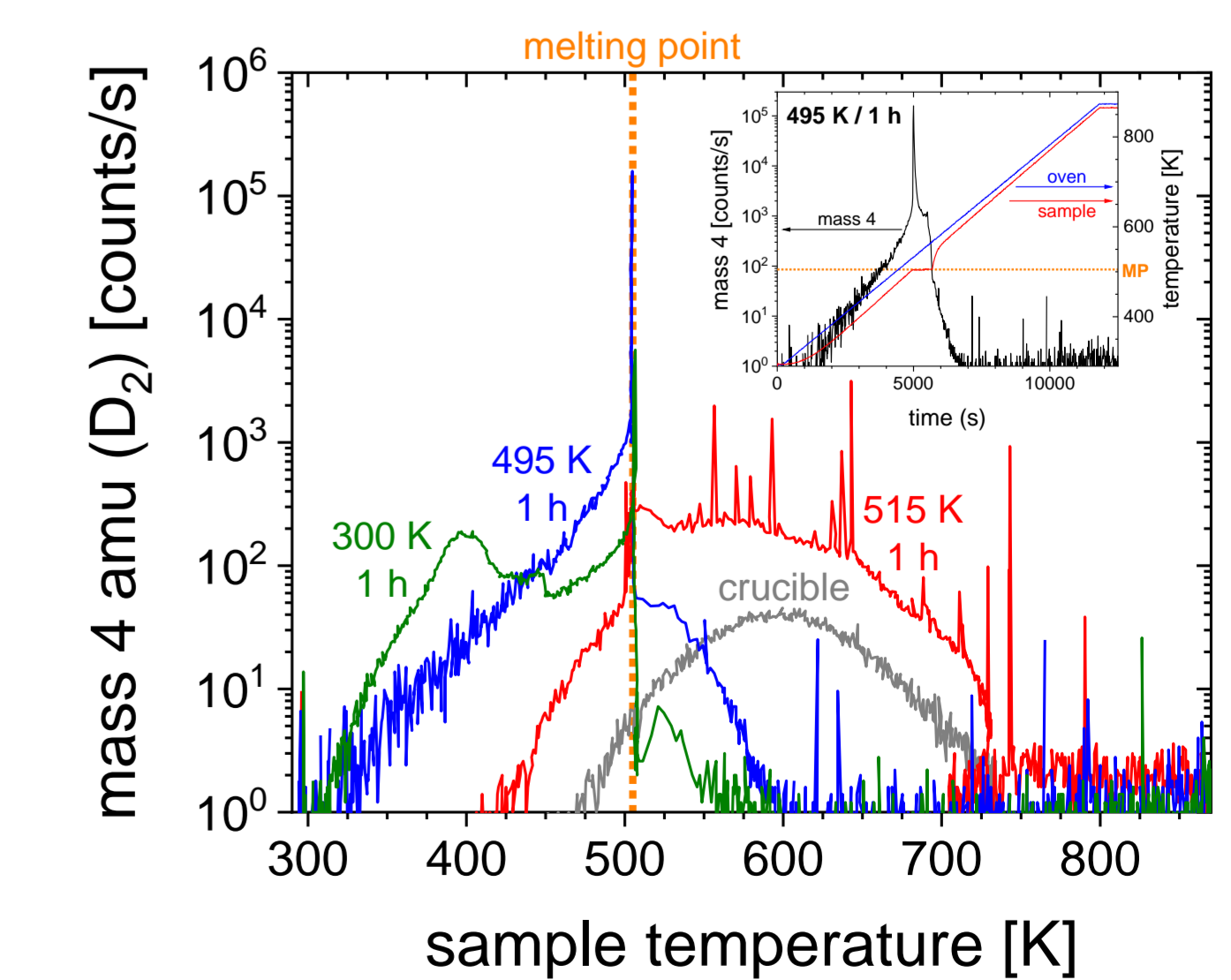
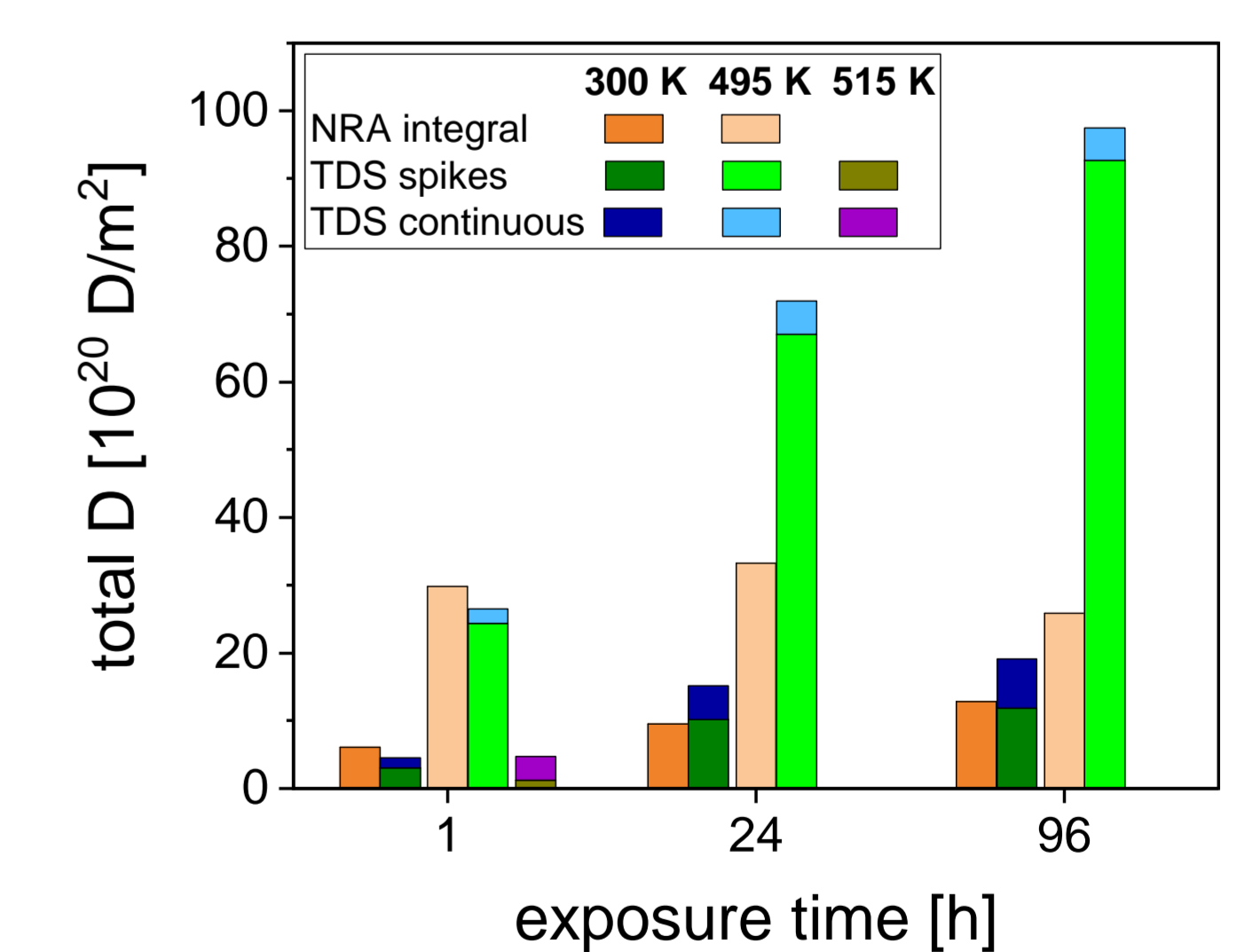
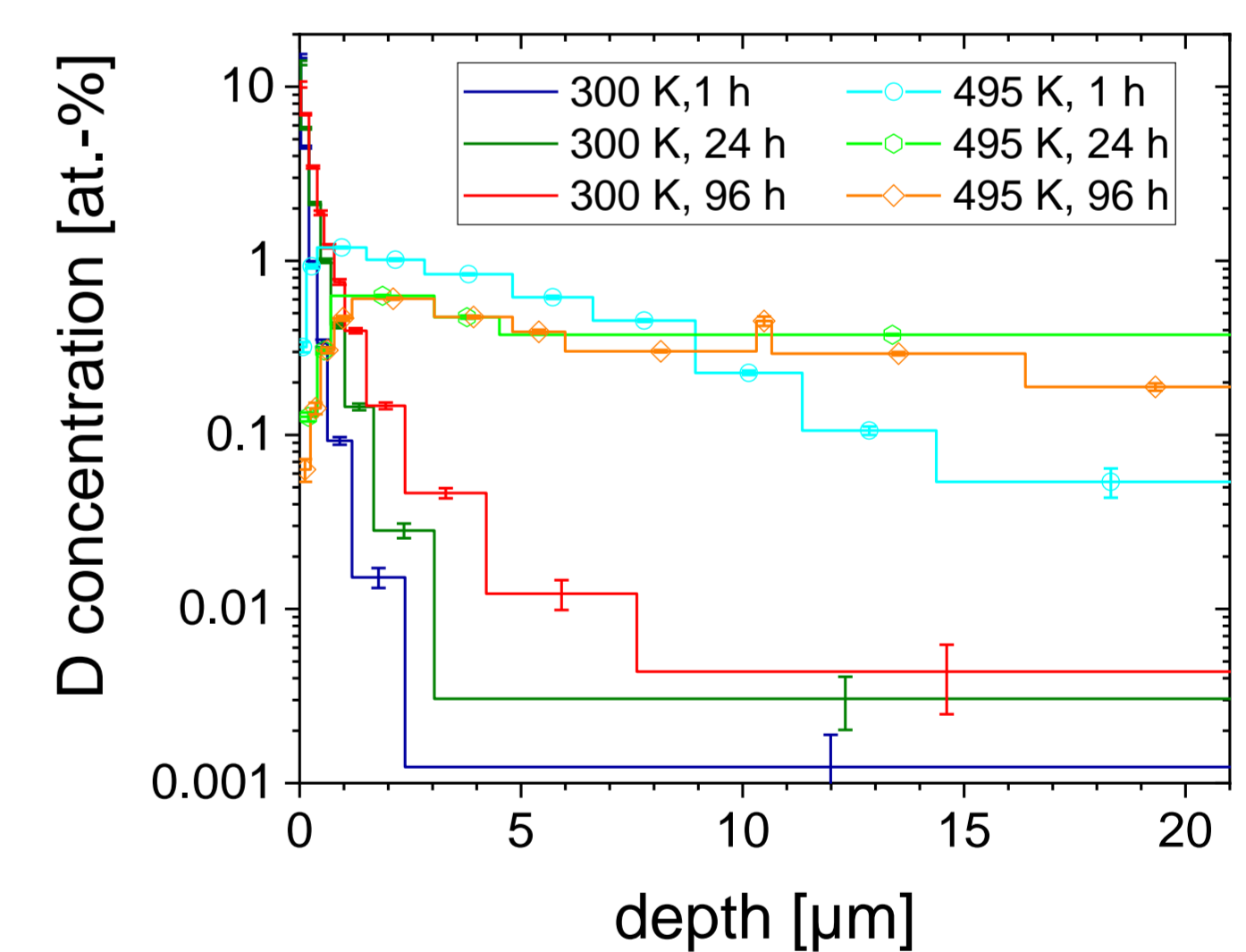
### References:

- [1] J.W. Coenen et al., Phys. Scr. T159 (2014) 014037  
 [2] M.B. Bever, C.F. Floe, Trans. AIME 156 (1944), 149-159  
 [3] A. Vertkov et al., Fus. Eng. Des. 117 (2017) 130-134  
 [4] D.T. Elg et al., Plasma Chem. Plasma Process. 38 (2018) 223-245  
 [5] T.W. Morgan et al., Plasma Phys. Control. Fusion 60 (2018) 014025  
 [6] A. Manhard et al., Plasma Sources Sci. Technol. 20 (2011) 015010  
 [7] A. Mutzke et al., SDTrimSP Version 6.00, IPP 2019-2 (2019)

## Deuterium retention & release

### Deuterium depth profiling: <sup>3</sup>He(D, p)<sup>4</sup>He NRA

- **300 K:**
  - D retention concentrated at surface
  - Increasing fluence  $\rightarrow$  growing tail into bulk
  - NRA total amount corresponds approximately to spike in TDS spectra
- **495 K:**
  - Larger total inventory, less peaked profiles
  - Depletion of D at surface  $\rightarrow$  sponge-like structure!
  - 1 h exposure: D contained mostly within first 20  $\mu$ m  $\rightarrow$  thickness of bubble layer!
  - Longer exposure times: significant amount of D beyond analysis range (compare also to TDS!)
- **515 K:**
  - D concentration in Sn at or below detection limit ( $\leq 5 \times 10^{-5}$  at.-%) within NRA range
  - D assumed to be mostly within gas bubbles



### Thermal Desorption Spectroscopy

- **Solid exposure (300 and 495 K; Sn without crucible):**
  - D<sub>2</sub> Release starts already at room temperature
  - Massive release spike at melting point
  - $\rightarrow$  Dominates D<sub>2</sub> release
  - $\rightarrow$  D release stops after end of melting phase
  - Additional peak at  $\sim 400$  K for 300 K exposure
  - D released almost exclusively as D<sub>2</sub>
- **Liquid exposure (515 K; Sn in crucible):**
  - Continuous signal + spikes
  - $\rightarrow$  D release continues until long after melting point
  - Smaller spikes  $\rightarrow$  bubbles rising to surface
  - Large spikes  $\rightarrow$  Sn droplet rising due to expansion of large gas bubble, and then collapsing
  - Strong HD release in addition to D<sub>2</sub>
  - In contrast to NRA: D retention comparable to sample exposed for 1 h at 300 K